

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GANG LI	10/12/2010
WEI HU	10/12/2010
RECEIVING PARTY DATA	
Name:	MEMSENSING MICROSYSTEMS TECHNOLOGY CO., LTD.
Street Address:	SUIT 213B, A2 BUILDING, BIOBAY, 218 XING HU ROAD, SUZHOU INDUSTRIAL PARK
City:	SUZHOU CITY, JIANGSU
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12910801
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Total Attachments: 2 source=WISPRO-00034-Assignment#page1.tif source=WISPRO-00034-Assignment#page2.tif	

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 REEL: 025184 FRAME: 0805

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the following inventor(s) (hereinafter as "ASSIGNORS")

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| 1. Name | <u>Li, Gang</u> |
| Residing at | <u>Suit 213B, A2 Building, BioBAY, 218 Xing Hu Road, Suzhou Industrial Park, China</u> |
| <hr/> | |
| 2. Name | <u>Hu, Wei</u> |
| Residing at | <u>Suit 213B, A2 Building, BioBAY, 218 Xing Hu Road, Suzhou Industrial Park, China</u> |
| <hr/> | |

hereby sell, assign, transfer, and set over to MEMSensing Microsystems Technology Co., Ltd of Suit 213B, A2 Building, BioBAY, 218 Xing Hu Road, Suzhou Industrial Park, China (hereinafter as "ASSIGNEE"), its successors and assigns, the entire right, title and interest in and to the invention known as METHODS FOR MANUFACTURING MEMS SENSOR AND THIN FILM THEREOF WITH IMPROVED ETCHING PROCESS (hereinafter as "INVENTION"), for which a United States Patent Application was executed concurrently herewith or, if not so executed, was:

- a. executed on _____ ;
b. filed on _____, Application Serial No. _____; or
c. established by PCT International Patent Application No. _____.

and all rights and privileges under any Letters Patent which may be granted thereon, including all rights, if any, to sue for past infringement.

The ASSIGNOR hereby agrees without charge to said ASSIGNEE but at its expense to execute all necessary papers to be used in connection with the above-identified application and any additional, substitute, continuing, divisional, reexamination, or reissue applications, as the ASSIGNEE may deem necessary or expedient; to execute all papers in connection with any interference or other legal or quasi-legal proceedings relating to the above-identified application or any additional, substitute, continuing, divisional, reexamination, reissue applications thereof; to cooperate with the ASSIGNEE in every way possible in obtaining evidence and going forward in any such proceedings; and to perform all other affirmative acts which may be necessary or desirable to obtain a grant of a valid patent for said INVENTION.

The ASSIGNOR hereby agrees to communicate to the ASSIGNEE, or its representatives, any facts known to the ASSIGNOR respecting said INVENTION, and testify in any legal proceedings, sign all lawful papers, execute all necessary assignment papers to cause any and all Letters Patent to be issued to the ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid the ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said INVENTION.

ASSIGNMENT (CONTINUED)

The ASSIGNOR hereby authorizes and requests the Commissioner of the United States Patent and Trademark Office to issue any and all Letters Patent that may be granted upon any patent application for the INVENTION or any additional, substitute, continuing, or divisional applications thereof to the ASSIGNEE, its successors and assigns.

The ASSIGNOR hereby covenants and warrants that the ASSIGNOR has full right to convey the entire right, title and interest in and to said INVENTION by this assignment, free of any encumbrances and that no other agreement has been or will be executed in conflict herewith.

Signature of
Inventor 1

Li Gang
Li, Gang

Executed Date

2010.10.12

Signature of
Inventor 2

Hu, Wei
Hu, Wei

Executed Date

2010.10.12